

CyberOptics SE500-X

High-Speed 3D Solder Paste Inspection for Demanding SMT Production

The CyberOptics SE500-X delivers fast, accurate inline solder paste inspection for high-performance SMT lines. Designed for demanding assemblies and larger panel formats, it helps manufacturers improve print quality, reduce defects, and increase process control.



KEY FEATURES



100% 3D solder paste inspection



Inspection speed greater than 70 cm²/sec



Detects pad sizes down to 01005 (150 μm x 150 μm)



Large-board capability: 100 x 100 mm up to 810 x 610 mm



Industry-leading volume accuracy and repeatability



3D height, area, and volume measurements



Automatic conveyor width adjustment



1D and 2D barcode reading



Process Tracker SPC charts with alarm capability



BUSINESS BENEFITS



Reduce print-related defects before placement



Improve first-pass yield and process stability



Support high-mix, high-throughput production



Strengthen closed-loop process control